7th ELECTRONICS SYSTEM-INTEGRATION TECHNOLOGY CONFERENCE

September 18-20, 2018

SECOND CALL FOR PAPERS

THE SINGLE LARGEST SEMICONDUCTOR PACKAGING CONFERENCE IN EUROPE

It is our pleasure to announce the **7th ESTC Conference**, the premier European scientific conference event in the field of microelectronics packaging and system integration. The conference will be held from 18th to 20th of September, 2018, at the Westin Bellevue Hotel in Dresden, Germany. This international event brings together both academics as well as the industry leaders to present and discuss state-of-the-art and the future trends in packaging and integration technologies. ESTC provides a perfect opportunity to learn about the latest developments in those fields. Save the date right now! This major event only takes place once every 2 years. ESTC is supported by IEEE-EPS in association with IMAPS-Europe. Read more at www.estc-conference.net. ESTC 2018 seeks original papers describing research and innovations in all areas of electronic packaging and system integration. You are invited to submit abstracts that provide non-commercial information of new developments and knowledge in areas like:

- Advanced packaging, 3D integration, embedded structures, wafer level packaging, TSVs, TEVs…
- Materials for interconnects and packaging, piezoelectric, dielectric and memory materials, nanomaterials…
- Optoelectronic systems packaging, fiber optical interconnects, optical sensors, LEDs and other photonic devices…
- Assembly and manufacturing technologies, wafer level processing…
- MEMS/NEMS and sensors packaging, bonding technologies, wafer bonding, micro-bonding…
- Design tools and modeling, thermal, mechanical and electrical modeling, signal and power integrity
- Power electronic systems packaging, power embedding, wide bandgap power semiconductor devices…
- Advanced technologies for emerging systems, allotropes of carbon, nano packaging, bio-electronics…
- Reliability of electronic devices and systems, characterization and test, failure diagnostic …
- Flexible printed and hybrid electronics, printed/jetted conductors, paper electronics, energy storage…

ABSTRACT SUBMISSION

You are invited to submit a 300 - 500 word abstract that describes the scope, content and key points of your proposed paper. Abstracts must include results and graphics. The official language of all presentations is English. Please visit www.estc-conference.net to find more information and to upload your abstract. Submission of abstracts will be open from December 1st 2017 and abstracts are due **February 15th 2018**. All abstracts must be submitted electronically at the conference website. All submitted abstracts will be reviewed by the committee to ensure high-quality of the conference. Authors will be notified of paper acceptance with instructions for publication by March, 30th 2018. If you have any questions, please contact: Karlheinz Bock, the General Chair of the 7th ESTC, via email karlheinz.bock@tu-dresden.de.

PUBLICATION OF PAPERS

All oral and poster presentation papers will be included in the conference proceedings and made available at the IEEE Xplore Digital Library (ieeexplore.ieee.org). In order to be included in IEEE Xplore, the paper must be original and not previously published, and avoid inclusion of commercial content.

ESTC 2018 Committee is proud to announce:

The **10% best ranked papers** of the conference will be invited to be published as journal publications in special sections of the **IEEE Transactions on Components, Packaging and Manufacturing Technology** after the conference. After an evaluation of the submitted full papers by the Technical Committee of ESTC authors of those papers will be informed and requested to adapt their full paper according to the transaction guidelines if necessary. Papers will then be grouped by topic of interest and published in the next upcoming issues of the journal.

Don't miss this opportunity to place a high ranked journal publication!

BEST PAPER AWARD

The ESTC Technical Committee will select the best paper presentation. The author(s) will receive a personalized ESTC award that comes with a 1.000 € prize money. The best poster paper will also be selected and the author(s) will receive a personalized ESTC award that comes with a 1.000 € prize money, too.

PROFESSIONAL DEVELOPMENT COURSES

In addition to abstracts for paper presentations, we call proposals from individuals interested in teaching Professional Development Courses (duration 4 hours) about the topics described in the Call for Papers. Up to four Professional Development Courses will be selected from the received proposals for Tuesday morning (September 18th, 2018) of the conference. Each selected course will be given an honorarium of 750 € if a minimum number of participants will sign in for the course. In addition, instructors of the selected courses will be offered the speaker discount rate for the conference. A 300 to 500 words proposal containing description of course objectives, course outline and who should attend, should be submitted to klaus-juergen.wolter@tu-dresden.de by February 15th, 2018.

IMPORTANT DATES

- **Website open for abstract submission: December 1st, 2017**
- **Abstract submission deadline: February 15th, 2018**
- **Notification of acceptance: March 30th, 2018**

General Chair:
Karlheinz Bock
Technische Universität Dresden, Germany

Executive Chair:
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Technische Universität Dresden, Germany

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